

For: **OXYGEN DOPED SIC FOR CU BARRIER AND ETCH STOP LAYER IN DUAL DAMASCENE FABRICATION**

Enclosed are:

<input checked="" type="checkbox"/>	<u>4</u> sheets of drawing(s) - formal.
<input checked="" type="checkbox"/>	An assignment of the invention to <b>Chartered Semiconductor Manufacturing Ltd.</b>
<input type="checkbox"/>	An associate power of attorney <input type="checkbox"/> Applicant claims small entity status
<input type="checkbox"/>	Request & Certification under 35 USC 122(b)(2)(b)(i)

The filing fee has been calculated as shown below:

	(Col. 1)	(Col. 2)	OTHER THAN A SMALL ENTITY	
FOR:	NO. FILED	NO. EXTRA	RATE	FEE
BASIC FEE				\$ 770.
TOTAL CLAIMS	37 -20=	17	x 18 =	\$ 306.
INDEP CLAIMS	3 -3=	0	x 86 =	\$ 0.
			SUB TOTAL	\$ 1,076.
			ASSIGNMENT	\$40.
			TOTAL	\$ 1,116.

☒ Please charge my Deposit Account No. 19-0033 in the amount of \$ **1,116**. A duplicate copy of this sheet is enclosed.

☒ The Commissioner is hereby authorized to charge payment of the following fees associated with this communication or credit any overpayment to Deposit Account No. 19-0033. A duplicate copy of this sheet is enclosed.

☒ Any additional filing fees required under 37 CFR §1.16.

☒ Any patent application processing fees under 37 CFR §1.17.

~~Respectfully submitted,~~

STEPHEN B. ACKERMAN, REG. NO. 37,761

# EXPRESS MAIL CERTIFICATE

Express Mail No. **EV385357788US**

I hereby certify that this correspondence is being deposited with the United States Postal Service as Express Mail in an envelope addressed to Assistant Commissioner of Patents, Alexandria, VA, 22313-1450. Applicant and/or Attorney requests the date of deposit as the Filing Date.

2/24/02  
Date of deposit

Signature / Date